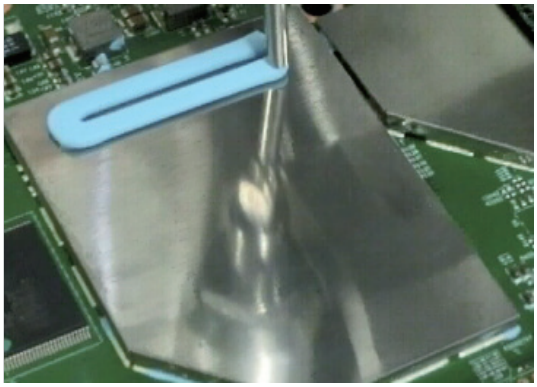
S-putty

Thermally Conductive Putty

LiPOLY S-putty is a one-part, fully cured, dispensable thermally conductive putty. With a thermal conductivity from 2.0 - 6.0 W/m*K this product can be used successfully to remove manufacturing tolerances. It is ideally suited for dispensing using the S-Putty dispensing robot.



Features-

- Thermal conductivity: 2.0/3.5/6.0 W/m*K
- Bond Line Thickness: 100-1500μm
- Designed to remove manufacturing tolerances
- Does not produce stress on delicate components
- No vertical flow
- Dispensable for serial manufacture
- UL 94V-0

Typical Applications-

- For any high compression and low stress application
- Set-top box
- IP CAM

Specifications-

- Cartridges: 30ml, 55ml, 330ml
- Bucket: 1kg, 25kg

Typical Properties-

PROPERTY	S-PUTTY5	S-PUTTY	S-PUTTY2	TEST METHOD	UNIT
Color	Blue	Blue	Blue	Visual	-
Resin Base	Silicone	Silicone	Silicone	-	-
Density	2.6	3	3.3	ASTM D792	g/cm³
Application temperature	-60~180	-60~180	-60~180	-	℃
Bond Line Thickness	100~1500	100~1500	100~1500	-	μm
ELECTRICAL					
Dielectric strength	300	300	300	ASTM D149	V/mil
Volume resistivity	>10^{13}	>10^{13}	>10^{13}	ASTM D257	Ohm-m
THERMAL					
Thermal Conductivity	2	3.5	6	ASTM D5470	W/m*K
Thermal Impedance @10psi	0.097	0.079	0.062	ASTM D5470	℃-in²/W
Thermal Impedance @ 30psi	0.089	0.071	0.059	ASTM D5470	℃-in²/W
Thermal Impedance @ 50psi	0.075	0.061	0.053	ASTM D5470	℃-in²/W
FLAME RATING					
UL Flammability class	V-0	V-0	V-0	UL94	-

※These data are provided for reference only. Engineers are reminded to test the material in varied application.

H-putty

Thermally Conductive Putty

LiPOLY H-putty is a one-part, fully cured, dispensable thermally conductive putty. With a thermal conductivity from 2.0 - 6.0 W/m*K this product can be used successfully to remove manufacturing tolerances. It is ideally suited for dispensing using the S-Putty dispensing robot.

Features-

- Thermal conductivity: 2.0/3.5/6.0 W/m*K
- Bond Line Thickness: 100-3000μm
- Designed to remove manufacturing tolerances
- Does not produce stress on delicate components
- No vertical flow
- Dispensable for serial manufacture
- UL 94V-0

Typical Applications-

- For any high compression and low stress application
- Set-top box
- IP CAM

Specifications-

- Cartridges: 30ml, 55ml, 330ml
- Bucket: 1kg, 25kg

Typical Properties-

PROPERTY	H-PUTTY5	H-PUTTY	H-PUTTY2	TEST METHOD	UNIT
Color	Blue	Blue	Blue	Visual	-
Resin Base	Silicone	Silicone	Silicone	-	-
Density	2.6	3	3.3	ASTM D792	g/cm³
Application temperature	-50~180	-50~180	-50~180	-	℃
Bond Line Thickness	100~3000	100~3000	100~3000	-	μm
ELECTRICAL					
Dielectric strength	300	300	300	ASTM D149	V/mil
Volume resistivity	>10^{14}	>10^{14}	>10^{14}	ASTM D257	Ohm-m
THERMAL					
Thermal Conductivity	2	3.5	6	ASTM D5470	W/m*K
Thermal Impedance @10psi	0.096	0.076	0.061	ASTM D5470	℃-in²/W
Thermal Impedance @ 30psi	0.087	0.072	0.054	ASTM D5470	℃-in²/W
Thermal Impedance @ 50psi	0.072	0.069	0.050	ASTM D5470	℃-in²/W
FLAME RATING					
UL Flammability class	V-0	V-0	V-0	UL94	-

※These data are provided for reference only. Engineers are reminded to test the material in varied application.